

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.26544	100.0	13.91631
			Subtotal	0.26544	100	13.91631
Die		Silicon (Si)	7440-21-3	0.7142	100.0	37.444
			Subtotal	0.7142	100	37.444
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.02384	5.0	1.25
	Pure metal	Silver (Ag)	7440-22-4	0.00715	1.5	0.375
	Pure metal	Lead (Pb)	7439-92-1	0.44585	93.5	23.375
			Subtotal	0.47684	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00796	100.0	0.41749
			Subtotal	0.00796	100	0.41749
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01894	0.03	0.993
	Copper alloy	Iron (Fe)	7439-89-6	0.06313	0.1	3.31
	Copper alloy	Copper (Cu)	7440-50-8	63.0524	99.87	3305.697
			Subtotal	63.13447	100	3310
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.66759	100.0	35
			Subtotal	0.66759	100	35
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.56301	4.5	81.945
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.47335	10.0	182.1
	Filler	Silica fused	60676-86-0	26.05012	75.0	1365.75
	Metal hydroxide	Metal hydroxide		3.47335	10.0	182.1
	Carbon Black	Carbon black	1333-86-4	0.17367	0.5	9.105
			Subtotal	34.7335	100	1821
			Total	100	100	5242.7778

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